

ABSTRACT

In a stacked package in which semiconductor chips are stacked in layers, in order to mount the semiconductor chips without damaging the semiconductor chips even when an upper semiconductor chip has a greater size, a first chip 12 is mounted on an interposer substrate 11. A second chip 13 having a larger size than that of the first chip 12 is mounted on the rear surface of the first chip 12. The second chip 13 is wire-bonded with respect to the interposer substrate 11 by wires 15. A base member 17 is disposed outside the first chip 12. The first chip 12, the second chip 13 and the base member 17 are molded by a sealing resin 16. Solder balls 18 are provided on the opposite side of the chip-mounting side of the interposer substrate 11.